

STAUF

— seit 1828 —



STAUF XP 20

Cement-based levelling compound



Technical Datasheet

Product number	✓ 133030
Special features	<ul style="list-style-type: none">✓ excellent levelling✓ coverings can be laid after short time✓ low-dust✓ easy to sand✓ surface low in pores
Application range	✓ levelling of floor screeds before bonding with STAUF wood flooring adhesives and adhesives for textile and elastic floorings
Suitable subfloors	<ul style="list-style-type: none">✓ sanded mastic asphalt screed✓ concrete C 25 / 30 according to DIN 1045 (non-skid surface)✓ calcium sulphate (flow) floors✓ wooden planks, wood fibre boards✓ magnesite and plaster floors✓ chipboards (P4 to P7), OSB boards (OSB/2 to OSB/4)✓ stone, ceramic, terrazzo, tiles✓ cement floors✓ cavity floors
Suitable primers	<ul style="list-style-type: none">✓ STAUF VDP 130✓ STAUF VPU 155 S + STAUF quartz sand✓ STAUF D 54✓ STAUF VDP 160✓ STAUF VEP 195 + STAUF quartz sand✓ STAUF WEP 180 + STAUF quartz sand
Product properties	<ul style="list-style-type: none">✓ up to 1 mm suitable for castors swivel chairs according to DIN EN 12529✓ suitable on subfloor heating systems✓ good absorbency✓ ductile during processing✓ high strength✓ pumpable✓ self-levelling✓ tension reducing✓ with STAUF reinforcing fibres also suitable for use on surfaces that are not dimensionally stable

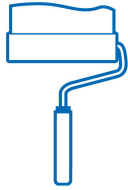
Color	✓ light grey
Consumption in g/m ² per mm layer thickness	✓ 1500g per mm layer thickness
Accessibility/ready for foot traffic	✓ after 2 hours at 20 °C, max 65% rel. humidity
Ready for installation	<ul style="list-style-type: none"> ✓ after 6 hours at 20 °C, (with 3 mm layer thickness) max 65% rel. humidity ✓ after 12 hours at 20 °C, (with 5 mm layer thickness) max 65% rel. humidity ✓ after 24 hours at 20 °C, (with 10 mm layer thickness) max 65% rel. humidity ✓ after 48 hours at 20 °C, (with 20 mm layer thickness) max 65% rel. humidity
Additional instructions 1	<ul style="list-style-type: none"> ✓ On chipboards / OSB boards: Add STAUF reinforcing fibres to levelling compound ✓ Without flammable constituents as per DIN 4102: A1 and DIN EN 13501: A1fl
Room climate at work site	✓ Minimum 18 °C, maximum 75% rel. humidity, preferably max. 65%
Transport requirements	✓ frost-free
Storage requirements	<ul style="list-style-type: none"> ✓ dry ✓ cool
Shelf-life	✓ 9 months
Giscode	✓ ZP1
Ecode	✓ EC1 plus
Available packaging	✓ 25 kg paper bag
layer thickness	<ul style="list-style-type: none"> ✓ 1 - 20 mm without aggregates ✓ 11 - 30 mm with aggregates ✓ min. 2 mm below wood flooring ✓ At least 2 mm under flexible floor coverings ✓ At least 1 mm under textile floor coverings ✓ mastic asphalt screed 2-5 mm
Processing time	✓ approx. 30 minutes at 20 °C and 65% rel. humidity
Mixing ratio component A	<ul style="list-style-type: none"> ✓ Layer thickness 1-20 mm: 25 kg filler ✓ layer thickness 11 - 30 mm: 25 kg levelling compound and 16 kg quartz sand ✓ fibre reinforcement: 25 kg levelling compound and 250g STAUF reinforcing fibres
Mixing ratio component B	<ul style="list-style-type: none"> ✓ layer thickness up to 5 mm: 6.5 liter water ✓ layer thickness at 5 mm: 6,25 liter water

EXAMINATION OF SUBFLOOR



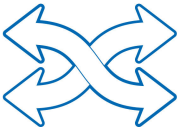
Before laying the covering, check the substrate in accordance with DIN 18356 and DIN 18365. The subfloor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of from contaminants that may prevent adhesion, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorption of subfloors as well as temperature, air humidity and subfloor temperature.

SUBFLOOR PREPARATION



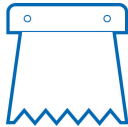
It must be ensured that the subfloor is ready for installation by performing proper subfloor preparation, floors must be clean, have sufficient surface strength, must be level, permanently dry and free of cracks. A mechanical pretreatment of the subfloor (sweeping, vacuuming, mechanical brushing, sanding, milling, shot blasting) must be performed depending on type and condition of subfloor. Cracks and joints, except expansion joints and other construction joints, shall be solidly closed with STAUF repair resin and floor brackets. Cavities and indentations can be filled with a non self-levelling STAUF levelling compound. In order to improve adhesion of adhesives and leveling compounds, prime the subfloor with the appropriate primer.

MIXING PROCEDURE OF COMPONENTS



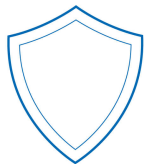
Add specified amount of water (clean and cold) into clean mixing bucket. Add complete content of container and stir evenly. For mixing, use an electrical stirrer with approx. 600 - 800 rpm with spiral or large paddle mixer. Mix until you have a homogeneous compound. Mix for another two minutes, wait one minute and then stir again for one minute (does NOT apply for non-self levelling compounds). Extending the levelling compound: To achieve higher layer thickness, the levelling compound can be extended with STAUF quartz sand. After levelling compound has been mixed with the specified amount of water, a max. of 16 kg of quartz sand may be added per bag of levelling compound. For reinforced levelling compound: Add 1 pouch (250 g) STAUF reinforcement fibers after initial stirring and then stir again for 2 minutes.

PROCESSING



Apply self-levelling compound within specified processing time. Do not pour the compound from mixing beaker on one spot only, but spread over a surface of approx. 2 x 2 m by changing position during pouring. Layer thickness can be controlled by using a wiper or a smoothing trowel. Air the levelling compound using a prickle roller. Self-levelling compounds do not require any additional mechanical spreading and form an even surface by themselves. Lower temperatures or higher ambient humidity delay the period until floor is ready for installation. The compound sets hydraulically, which means that it needs to be protected from direct sunlight and draughts. Before applying a further layer of filler or levelling compound, apply an intermediate layer of STAUF dispersion primer for filler compounds. Do not prime levelling and filler compounds before direct adhesion. For chipboard and OS panels, layer thicknesses of up to 5 mm are admissible. On less absorbent substrates and under flexible coverings, layer thickness of at least 2 mm.

LIMITATION OF LIABILITY



The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior on-site testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.

